

## **ASMPT Forms Technical Advisory Council to Accelerate AI-Era Innovation**

*Council brings together senior industry and academic leaders to advise ASMPT on advanced packaging roadmaps, AI-enabling interconnect, and ecosystem collaboration*

SINGAPORE, 28 May 2026 — ASMPT (HKEX: 0522) announced the formation of its Advanced Packaging Technology Advisory Council (TAC), an independent advisory body established to provide strategic guidance to ASMPT's management on its Research & Development roadmap as advanced packaging (AP) becomes increasingly critical to enabling next-generation computing and AI components and systems.

As the semiconductor industry advances beyond traditional scaling, AP plays a fundamental role in expanding component and system capabilities. For the TAC, ASMPT's scope of AP encompasses next-generation packaging formats and emerging trends — including advanced memory (HBM & HBF), CoWoS & EMIB-T and associated derivatives, photonics, Near-Packaged Optics and Co-Packaged Optics, and devices that support 2.5D/3D/3.5D heterogeneous integration eco-systems.

"The AI era is raising the bar for advanced packaging — in performance, and manufacturability; this makes clarity of roadmap definition, technology development, and excellence in execution even more important," said **Lim Choon Khoon, ASMPT's Chief Counsel for Advanced Packaging**. "By convening highly respected experts and industry luminaries across advanced packaging, operations, quality, and research, the ASMPT Technical Advisory Council will strengthen our ability to anticipate and react to technology inflections, align to customer and end-user roadmaps, and accelerate innovation that helps our customers scale AI and next-generation computing."

The TAC acts as an independent advisory body that will provide recommendations and perspectives to ASMPT's management through its Secretariat on key focus

areas. It brings together leaders with deep expertise spanning AP technology development, assembly and test, manufacturing operations and quality, and academic research:

- Dr. Gaurang Choksi — Former Vice President, Technology Development, Intel Corporation (Chair)
- Dr. Babak Sabi — Former Vice President, Annapurna Lab, AWS; Former Intel Senior Vice President, Assembly & Test Technology Development
- Mr. Vincent Tong — Head of Global Operations & Quality, Altera; former EVP of Global Operations at Xilinx and former Chief Quality Officer at AMD
- Dr. Devan (Mahadevan) Iyer — Chief Strategist, Advanced Electronic Packaging, Global Electronics Association
- Dr. Jae-Inh Song — Professor, Hanyang University-ERICA; Former ASM executive (VP Global Business Operations & New Business Development)

“Advanced packaging has become one of the most critical levers for scaling compute and AI systems, and the pace of innovation continues to accelerate,” said **Dr. Gaurang Choksi, Chair of the ASMPT TAC**. “ASMPT is at the forefront of advanced packaging technologies, and I am honored to contribute my perspective alongside distinguished colleagues. Together, we aim to advise ASMPT on technology roadmaps and the practical considerations necessary to translate packaging innovation into manufacturable, reliable solutions.”

### **About ASMPT Limited**

ASMPT is a leading global supplier of hardware and software solutions for the manufacture of semiconductors and electronics. Headquartered in Singapore, ASMPT’s offerings encompass the semiconductor assembly & packaging, and SMT (surface mount technology) industries, ranging from wafer deposition to the various solutions that organise, assemble and package delicate electronic components into a vast range of end-user devices. ASMPT partners with customers very closely, with continuous investment in R&D helping to provide cost-effective, industry-leading solutions that achieve higher productivity, greater reliability and enhanced quality.

ASMPT is listed on the Stock Exchange of Hong Kong (HKEX stock code: 0522) and is one of the constituent stocks of the HKEX Tech 100 Index, Hang Seng Composite MidCap Index under the Hang Seng Composite Size Indexes, the Hang Seng Composite Information Technology Industry Index under Hang Seng Composite Industry Indexes, the Hang Seng Corporate Sustainability Benchmark Index, and the Hang Seng HK 35 Index. To learn more about ASMPT, please visit us at [www.asmpt.com](http://www.asmpt.com).

Forward-Looking Statements: This press release contains forward-looking statements that are based on ASMPT’s current beliefs, assumptions and information currently available. Actual results may differ

materially due to a number of risks and uncertainties. ASMPT undertakes no obligation to update any forward-looking statements publicly.